PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data		
1.1 Company		STMicroelectronics International N.V
1.2 PCI No.		ADG/17/10129
1.3 Title of PCI		SPC560D30L1x and SPC560D40L1x (FB40): Laser Grooving and Low Stress Molding Compound Implementation
1.4 Product Category		see list
1.5 Issue date		2017-02-27

2. PCI Team		
2.1 Contact supplier		
2.1.1 Name	ROBERTSON HEATHER	
2.1.2 Phone	+1 8475853058	
2.1.3 Email	heather.robertson@st.com	
2.2 Change responsibility		
2.2.1 Product Manager	Luca RODESCHINI	
2.1.2 Marketing Manager	Daniele Alfredo BRAMBILLA	
2.1.3 Quality Manager	Alberto MERVIC	

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), lead frame, resin, wire, …)	ST Kirkop (Malta)

4. Description of change			
Old New			
4.1 Description	Die Sawing and Molding Compound Sumitomo G700L	Laser Sawing and Molding Compound Sumitomo G700LS	
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact		

5. Reason / motivation for change	
5.1 Motivation	Quality Improvement
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change	
6.1 Description	Dedicated Finished Good Codes

7. Timing / schedule		
7.1 Date of qualification results	2017-02-22	
7.2 Intended start of delivery	2017-05-19	
7.3 Qualification sample available?	Upon Request	

8. Qualification / Validation			
8.1 Description	10129 Qualification reports.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2017-02-27

9. Attachments (additional documentations)

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	0.1.1 Customer Part No 10.1.2 Supplier Part No 10.1.2 Supplier Part No	
	SPC560D40L1C4E0X	

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Public Products List

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PCI Title : SPC560D30L1x and SPC560D40L1x (FB40): Laser Grooving and Low Stress Molding Compound Implementation *PCI Reference :* ADG/17/10129

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

SPC560D40L1C4E0Y	SPC560D30L1B4E0X	SPC560D40L1C4E0X
SPC560D40L1B3E0X	SPC560D40L1B4E0X	

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